DATA SHEET



MOS FIELD EFFECT TRANSISTOR 2SK4092

SWITCHING N-CHANNEL POWER MOS FET

DESCRIPTION

The 2SK4092 is N-channel MOS FET device that features a low gate charge and excellent switching characteristics, and designed for high voltage applications such as switching power supply, AC adapter.

FEATURES

· Low on-state resistance

 $R_{DS(on)} = 0.4 \Omega MAX. (V_{GS} = 10 V, I_{D} = 10 A)$

Low gate charge

 $Q_G = 50 \text{ nC TYP}$. $(V_{DD} = 450 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 21 \text{ A})$

- Gate voltage rating: ±30 V
- Avalanche capability ratings

ORDERING INFORMATION

PART NUMBER	LEAD PLATING	PACKING	PACKAGE
2SK4092-A Note	Sn-Ag-Cu	100 p/package	TO-3P (MP-88) typ. 5.0 g

600

29.4

Α

mJ

Note Pb-free (This product does not contain Pb in the external electrode and other parts.)

ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

	O (1/4 = 20 O)
Drain to Source Voltage (VGS = 0 V)	Voss

Gate to Source Voltage (VDS = 0 V) Vgss ±30 Drain Current (DC) (Tc = 25°C) ±21 Α ID(DC) Drain Current (pulse) Note1 ±60 I_{D(pulse)} Total Power Dissipation (Tc = 25°C) P_{T1} 200 W Total Power Dissipation (T_A = 25°C) P_{T2} 3 **Channel Temperature** Tch 150 ٥С Storage Temperature Tstq -55 to +150 °C Single Avalanche Current Note2 21

las

Eas

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

Single Avalanche Energy Note2

2. Starting T_{ch} = 25°C, V_{DD} = 150 V, R_G = 25 Ω , V_{GS} = 20 \rightarrow 0 V

(TO-3P)



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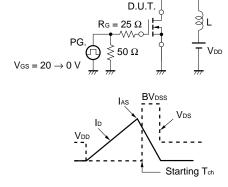
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ELECTRICAL CHARACTERISTICS (TA = 25°C)

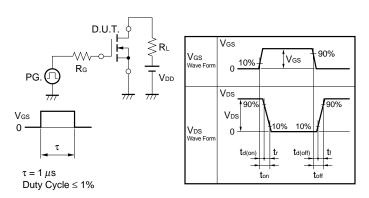
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	V _{DS} = 600 V, V _{GS} = 0 V			10	μΑ
Gate Leakage Current	Igss	V _{GS} = ±30 V, V _{DS} = 0 V			±100	nA
Gate to Source Cut-off Voltage	V _{GS(off)}	V _{DS} = 10 V, I _D = 1 mA	2.5	3.0	3.5	V
Forward Transfer Admittance Note	y _{fs}	V _{DS} = 10 V, I _D = 10 A	4.0			S
Drain to Source On-state Resistance Note	R _{DS(on)}	V _{GS} = 10 V, I _D = 10 A		0.34	0.4	Ω
Input Capacitance	Ciss	V _{DS} = 10 V,		3240		pF
Output Capacitance	Coss	V _{GS} = 0 V,		550		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		3		pF
Turn-on Delay Time	t _{d(on)}	V _{DD} = 150 V, I _D = 10 A,		38		ns
Rise Time	tr	V _{GS} = 10 V,		15		ns
Turn-off Delay Time	t _{d(off)}	R _G = 10 Ω		58		ns
Fall Time	tf			12		ns
Total Gate Charge	Q _G	V _{DD} = 450 V,		50		nC
Gate to Source Charge	Qgs	V _{GS} = 10 V,		24		nC
Gate to Drain Charge	Q _{GD}	I _D = 21 A		17		nC
Body Diode Forward Voltage Note	V _{F(S-D)}	IF = 21 A, V _{GS} = 0 V		0.9	1.5	V
Reverse Recovery Time	trr	I _F = 21 A, V _{GS} = 0 V,		480		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/ <i>μ</i> s		6000		nC

Note Pulsed

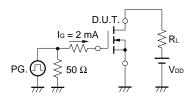
TEST CIRCUIT 1 AVALANCHE CAPABILITY



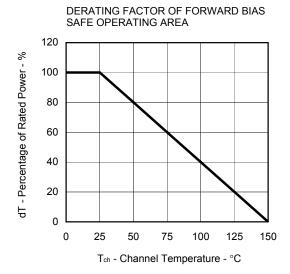
TEST CIRCUIT 2 SWITCHING TIME

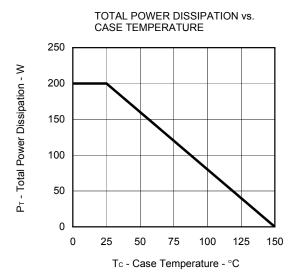


TEST CIRCUIT 3 GATE CHARGE

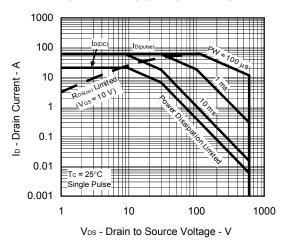


TYPICAL CHARACTERISTICS (T_A = 25°C)

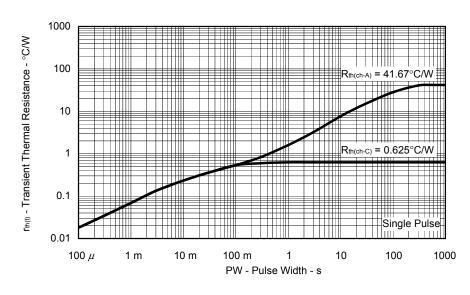




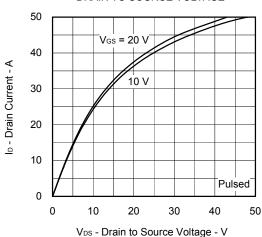
FORWARD BIAS SAFE OPERATING AREA



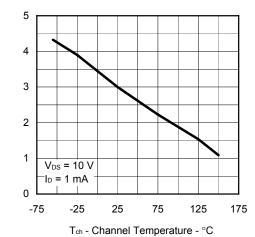
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



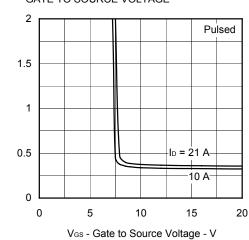
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



GATE TO SOURCE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE

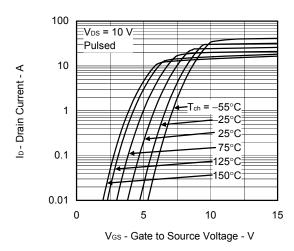


DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

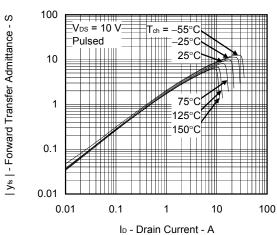


FORWARD TRANSFER CHARACTERISTICS

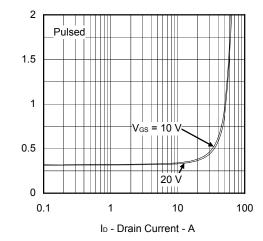
2SK4092



FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

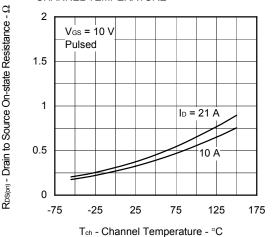


 $\mathsf{R}_{\mathsf{DS}(\varpi)}$ - Drain to Source On-state Resistance - Ω

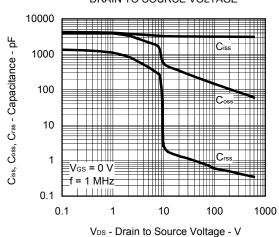
Ves(off) - Gate to Source Cut-off Voltage - V

 $\mathsf{R}_{\mathsf{DS}(\varpi)}$ - Drain to Source On-state Resistance - Ω

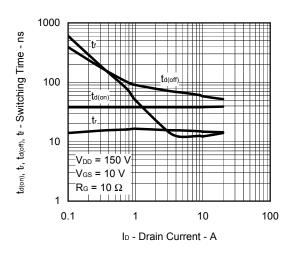
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



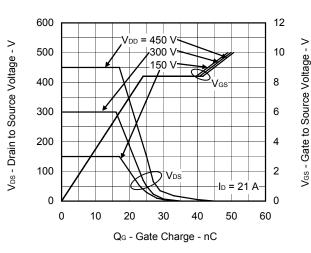
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



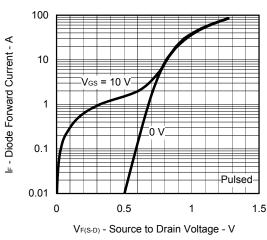
SWITCHING CHARACTERISTICS



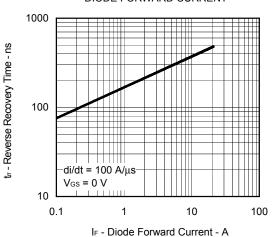
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



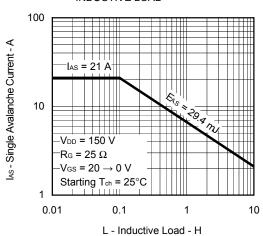
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



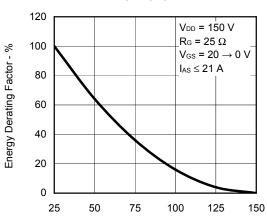
REVERSE RECOVERY TIME vs. DIODE FORWARD CURRENT



SINGLE AVALANCHE CURRENT vs. INDUCTIVE LOAD



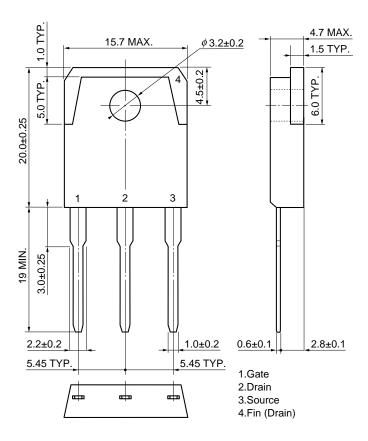
SINGLE AVALANCHE ENERGY DERATING FACTOR



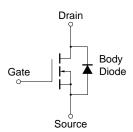
Starting T_{ch} - Starting Channel Temperature - $^{\circ}$ C

PACKAGE DRAWING (Unit: mm)

TO-3P (MP-88)



EQUIVALENT CIRCUIT



Remark Strong electric field, when exposed to this device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred.

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